

Method for mounting semiconductors provided with bumps on substrate locations of a substrate

Abstract

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The invention relates to a method for mounting semiconductor chips provided with bumps as flip chips on substrate locations of a substrate. The method comprises the placing of a flip chip in a cavity arranged in a stationary manner where the bumps are wetted with a fluxing agent and the position of the flip chip is determined by means of a camera. The method further comprises the use of a transport head and a bonding head, which allow rapid and highly precise mounting.

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(Fig. 1)